

Electroplating Head and Method for Operating the Same

ABSTRACT OF THE DISCLOSURE

5 An electroplating head including a chamber having a fluid entrance and a fluid exit is provided. The chamber is configured to contain a flow of electroplating solution from the fluid entrance to the fluid exit. The electroplating head also includes an anode disposed within the chamber. The anode is configured to be electrically connected to a power supply. The electroplating head further includes a porous resistive material disposed at the fluid exit such that the flow of electroplating solution is required to
10 traverse through the porous resistive material.

Figure 1